



CKT. SIZE	DIM. A REF.		DIM. B REF.	
	(MM)	(INCH)	(MM)	(INCH)
4	(2.54)	.100	(4.83)	.190
6	(5.08)	.200	(7.37)	.290
8	(7.62)	.300	(9.91)	.390
10	(10.16)	.400	(12.45)	.490
12	(12.70)	.500	(14.99)	.590
14	(15.24)	.600	(17.53)	.690
16	(17.78)	.700	(20.07)	.790
18	(20.32)	.800	(22.61)	.890
20	(22.86)	.900	(25.15)	.990
22	(25.40)	1.000	(27.69)	1.090
24	(27.94)	1.100	(30.23)	1.190
26	(30.48)	1.200	(32.77)	1.290
28	(33.02)	1.300	(35.31)	1.390
30	(35.56)	1.400	(37.85)	1.490
32	(38.10)	1.500	(40.39)	1.590
34	(40.64)	1.600	(42.93)	1.690
36	(43.18)	1.700	(45.47)	1.790
38	(45.72)	1.800	(48.01)	1.890
40	(48.26)	1.900	(50.55)	1.990
42	(50.80)	2.000	(53.09)	2.090
44	(53.34)	2.100	(55.63)	2.190
46	(55.88)	2.200	(58.17)	2.290
48	(58.42)	2.300	(60.71)	2.390
50	(60.96)	2.400	(63.25)	2.490
52	(63.50)	2.500	(65.79)	2.590
54	(66.04)	2.600	(68.33)	2.690
56	(68.58)	2.700	(70.87)	2.790
58	(71.12)	2.800	(73.41)	2.890
60	(73.66)	2.900	(75.95)	2.990
62	(76.20)	3.000	(78.49)	3.090
64	(78.74)	3.100	(81.03)	3.190
66	(81.28)	3.200	(83.57)	3.290
68	(83.82)	3.300	(86.11)	3.390
70	(86.36)	3.400	(88.65)	3.490
72	(88.90)	3.500	(91.19)	3.590
74	(91.44)	3.600	(93.73)	3.690
76	(93.98)	3.700	(96.27)	3.790
78	(96.52)	3.800	(98.81)	3.890
80	(99.06)	3.900	(101.35)	3.990

- NOTES:**
- 1 - PIN PUSHOUT FORCE: 4 LBS. MINIMUM
 - 2 - FOR ILLUSTRATION PURPOSES, 20 (DUAL 10) CIRCUIT SIZE IS SHOWN.
 - 3 - PINS MUST MEET SOLDERABILITY SPEC. ES-152, EXCEPT VOIDS ARE PERMISSIBLE AT BANDOLIER PIN FAYING SURFACE. (APPROX. .025 LNC X .006 WD. REF.) - 2 LOCATIONS
 - 4 - WAFER TO BE FLAT WITHIN (0.03 MM/CM) / (0.03 IN./IN.)
 - 5 - MEASURE POINT FOR PLATING THICKNESS.
 - 6 - THIS PRODUCT CONFORMS TO MOLEX PRODUCT SPEC. PS-70203.
 - 7 - FOR ASSEMBLIES WITH VOIDS, REFER TO DRAWING NUMBER SDA-70203-5001-9999.
 - 8 - PACKAGING INFORMATION: (UNLESS OTHERWISE NOTED IN TABLES)
CIRCUIT SIZE: 4 THROUGH 8, 10 AND OVER
PACKAGING DRAWING: PK-70873-0353, PK-70873-0075

- FINISH:**
- TIN - .000150 MINIMUM TIN PLATE OVER NICKEL PLATE.
 - 15 GOLD - .000015 MINIMUM GOLD PLATE IN SELECT AREA, .000075 MINIMUM TIN PLATE IN SELECT AREA, OVER NICKEL PLATE OVERALL.
 - 30 GOLD - .000030 MINIMUM GOLD PLATE IN SELECT AREA, .000075 MINIMUM TIN PLATE IN SELECT AREA, OVER NICKEL PLATE OVERALL.
- *THE PRIMARY SHIPPING CARTON WILL BE LABELED 'COMPLIANT TO RoHS DIRECTIVE 2002/95/EC AND ELV ANNEX II OF DIRECTIVE 2000/53/EC'. CARTONS WITHOUT THIS LABEL MAY CONTAIN PRODUCT WITH LEAD.

MATERIAL:

WAFER - G.F. POLYESTER; 94V-0; COLOR: BLACK
PIN - PHOSPHOR BRONZE

D	LEAD FREE UCP2004-1770 RWHITE 04/04/23
CI	REVISE PKNGNG ECN UDT2000-0949 SCHAFER 00/4/6
C	REVISED PER ECN # U60711 1/8/96 BJS/RCB
BI	ADDED EDP # 5 PER ECR # U60256 95/08/23 CAC
B	VOIDED EDP NO'S PER ECR # U60097 95/07/27 CAC
A	RELEASED PER ECR # U31656 11/18/93 REED

REVISIONS

2	D			
1	D			

MFG. SH. REV. LTR. REVISIONS

REVISIONS ONLY ON CAD SYSTEM

SALES ASSY-DUAL ROW
WAFER W/BREAK-OFF OPTION
RIGHT ANGLE/.025 SQ PINS

MOLEX INCORPORATED
68532 U.S.A.

DATE: 11/18/93

SEE CHART ISDA-70203-0001-5000

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